DS04-27502-3E

# ASSP For Power Supply Applications

# BI-CMOS Battery Backup IC

# **MB3790**

# DESCRIPTION

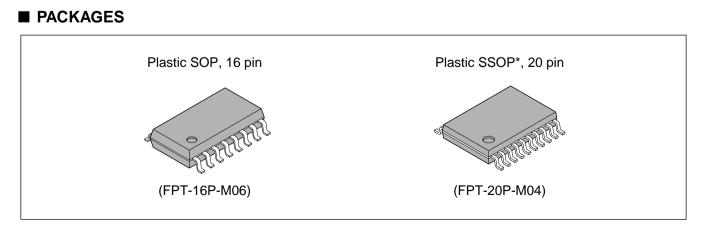
The MB3790 is designed to control power supplies to SRAM, logic IC, or other circuit devices and protects them against momentary power failures by using backup batteries. In addition to its function to supply the power to these devices, it has a function to switch the source of power to the primary or secondary backup battery when the power supply voltage drops below a predetermined level. Also, it outputs a reset signal when the power supply turns on or off or when a fault occurs in the power supply.

Ideally designed as a single-chip IC for power supply control, the MB3790 consumes only a minimal current and comes in a thin-type package. Therefore, it is best suited for power supply control in memory cards and similar other devices.

# FEATURES

- Input circuit current consumption when non-loaded: 50 μA [typ]
- Output drive current: 200 mA [max]
- Resistance between input and output: 0.5 ohms [typ]
- Input power-down detection level: 4.2 V  $\pm$  2.5 %
- On-chip power-on reset circuit
- Primary battery voltage-down detection levels: 2.65 V, 2.37 V

(Continued)



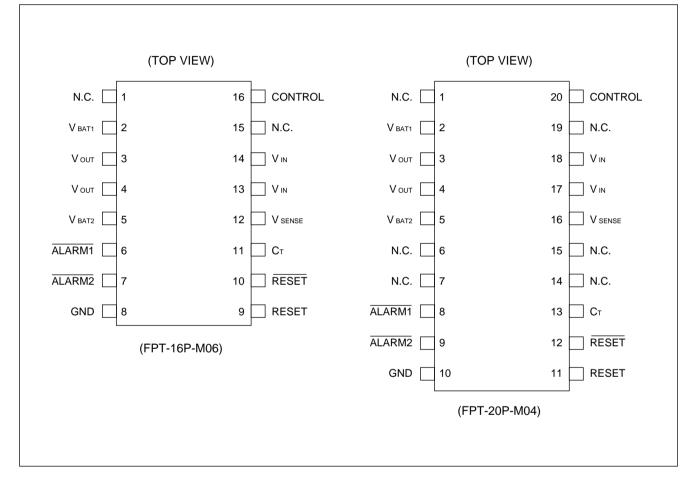
\* : Since the SSOP is an extremely thin package, use a partial heating method when mounting the device.

# MB3790

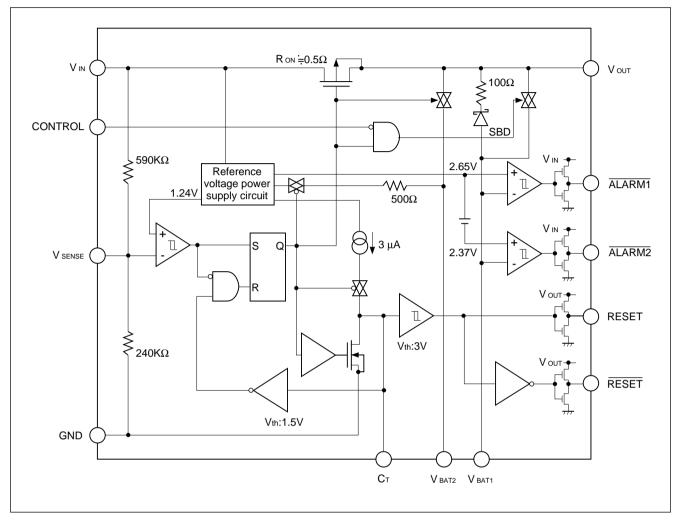
### (Continued)

- On-chip secondary battery recharging function
- Output current during battery backup: VBAT1: 500 μA [max], VBAT2: 50 μA [max]
- Leakage current: 0.5 μA [max]

# PIN ASSIGNMENTS



### ■ BLOCK DIAGRAM



# ■ PIN DESCRIPTION

Pin number		Symbol I/O		Name and function		
16P	20P	Symbol	1/0	Name and function		
1	1	N.C.	_	Non connection		
2	2	VBATI	I	This pin connects to the primary battery.		
3, 4	3, 4	Vout	0	These pins supply the output voltage. (Range of output current value $I_{\text{OUT}} \leq 200 \text{ mA})$		
5	5	Vbat2	I/O	This pin connects to the secondary battery. When the power supply voltage is greater than or equal to the detection level (i.e., $V_{\text{INH}}$ ), the secondary battery is recharged using the constant-voltage method of charging.		
-	6, 7	N.C.		Non connection		
6	8	ALARM1	0	This is an open-collector output pin for a primary battery alarm signal. When the power supply voltage is greater than or equal to $V_{INH}$ , it monitors the primary battery voltage. If the power supply voltage is less than $V_{INL}$ , it does not monitor the primary battery voltage. If $V_{BAT1}$ is less than or equal to 2.65 V, its output voltage is forced to a Low level.		
7	9	ALARM2	0	This is an open-collector output pin for a primary battery alarm signal. When the power supply voltage is greater than or equal to $V_{INH,}$ it monitors the primary battery voltage. If the power supply voltage is less than $V_{INL}$ , it does not monitor the primary battery voltage. If $V_{BAT1}$ is less than or equal to 2.37 V, its output voltage is forced to a Low level.		
8	10	GND	—	This pin connects to the ground (0 V).		
9	11	RESET	0	This pin connects to the ground (o v). This pin outputs a reset signal. When the power supply voltage is less than or equal to V <sub>INL</sub> , it outputs a High level. If the power supply voltage of SRAM is less than the designated range, it directly controls the CE or CS of SRAM to disable writes and thereby protect the data in memory.		
10	12	RESET	0	This pin outputs an inverted signal of RESET.		
11	13	Ст		This pin is used to set the reset pulse width. Insert a capacitor between this pin and GND to set the pulse width.		
—	14, 15	N.C.		Non connection		
12	16	Vsense	Ι	This pin accepts comparator input for detecting the power supply voltage level. For details, refer to APPLICATION in this data sheet.		
13, 14	17, 18	Vin	I	These pins accept the input voltage for the device.		
15	19	N.C.		Non connection		
16	20	CONTROL	I	This pin is used for output control. For details, refer to APPLICATION in this data sheet.		

# ■ FUNCTIONAL DESCRIPTION

### 1. Battery Backup Function

- When the power supply voltage exceeds the voltage detection level (i.e., VINH), the device outputs a current of up to 200 mA from the VIN power supply to the load circuit via the VOUT pin.
- When the power supply voltage is less than or equal to V<sub>INL</sub>, the device switches the source of power for V<sub>OUT</sub> from V<sub>IN</sub> to the primary or secondary battery for backup purposes.

### 2. Power Supply Voltage Level Detect Function

When the power supply voltage drops below V<sub>INL</sub>, the voltage level detection comparator is actuated to perform the following (note that the detection voltage level has the hysteresis characteristics listed in ELECTRICAL CHARAC-TERISTICS in this data sheet):

- The comparator first outputs the RESET signal (High level).
- It switches the source of power for the load circuit to the primary or secondary battery.

The power supply voltage detection level can be adjusted by fitting an external resistor to the  $V_{\text{SENSE}}$  pin. When adjusting the detection level, be sure to set it to 4.0 V or higher by considering the power supply voltage for the internal circuit operation.

In addition, the detection set time can be extended by connecting a capacitator. For this method of adjustment, refer to APPLICATION in this data sheet.

### 3. Reference Voltage Circuit

This is a temperature-compensated reference voltage circuit of a band gap type so that it outputs a trimmingadjusted exact reference voltage.

The reference voltage power supply is used to set the reference voltage/constant current values of the detection circuit, as well as the secondary battery recharging voltage.

### 4. Power-on Reset Function

By charging the capacitator connected to the  $C_T$  pin with constant current (approx. 3  $\mu$ A), this function determines the reset pulse width. The calculation formula for this is given below:

Reset pulse width  $t_{\text{PO}} \; (sec) \cong C_{\text{T}} \; (F) \times 10^6$ 

(When  $C_T = 1000 \text{ pF}$ ,  $t_{PO} \cong 1 \text{ ms} \text{ [typ]}$ )

### 5. Primary Battery Voltage Detection Function

If the primary battery voltage drops below the detection level when the power supply voltage is greater than or equal to  $V_{INL}$ , the device outputs an alarm signal (Low level) from the CMOS output pin, ALARM1 or ALARM2.

Note that the voltage level detection comparator has the hysteresis characteristics listed in ELECTRICAL CHAR-ACTERISTICS in this data sheet.

• When the primary battery voltage is 2.65 V [typ] or less:

The ALARM1 output pin is forced to a Low level to issue an alarm indicating that it's time to replace the primary battery.

• When the primary battery voltage is 2.37 V [typ] or less:

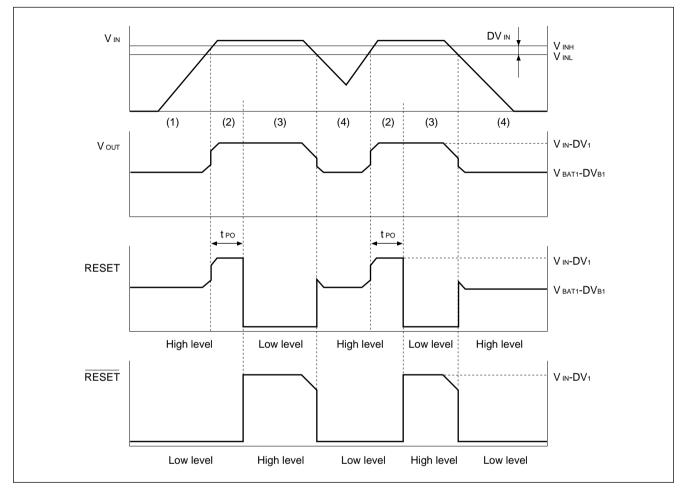
The ALARM2 output pin is forced to a low level to issue an alarm indicating that the primary battery voltage is less than the voltage necessary to retain the SRAM data (approx. 2.0 V)

### 6. Secondary Battery Recharging Function

When the power supply voltage is greater than or equal to V<sub>INL</sub>, the device recharges the secondary battery using the constant-voltage method of charging. Note that the typical value of the device's internal recharging resistor is 500 ohms.

## DESCRIPTION OF OPERATION

### 1. Operation When the Input Voltage Goes On or Off



### (1) Power-on

While the power supply voltage is less than  $V_{INH}$  (4.3 V typ), the protected devices such as SRAM or a microprocessor are in the standby mode with the power supplied by the battery.

When the power supply voltage rises to a level greater than or equal to  $V_{INH}$ , the PMOS transistor between the input/ output pins turns on and the power for such devices is supplied from the  $V_{IN}$  pin. At the same time, the primary battery voltage detection and the secondary battery recharging operations are actuated.

### (2) Standby mode

When the power supply voltage rises to a level greater than or equal to  $V_{INH}$ , the RESET pin outputs a High level for the set duration of time and the devices such as SRAM or a microprocessor are held in the standby mode. Note that the set duration of time can be adjusted by changing the capacitance of the C<sub>T</sub> pin.

The **RESET** pin outputs an inverted signal of the **RESET** pin.

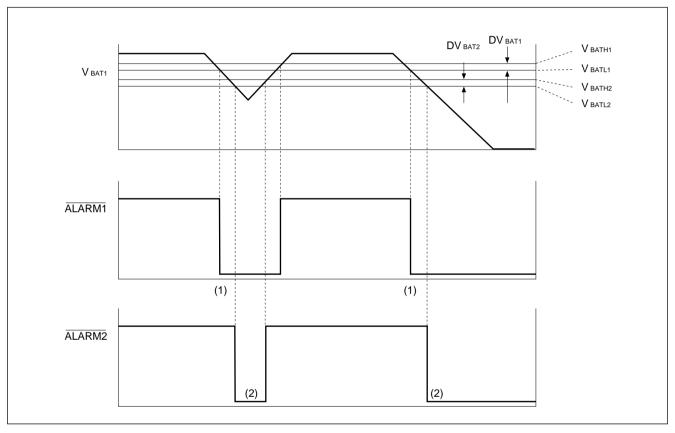
### (3) Active mode

The reset signal is cleared and the devices such as SRAM or a microprocessor are placed in the operating mode.

### (4) Momentary power failure or voltage dip

When the power supply voltage drops less than or equal to  $V_{INL}$ . (4.2 V typ) as the power supply goes down or its voltage dips momentarily, the RESET pin outputs a High level and the RESET pin outputs a low level. The devices such as SRAM or a microprocessor are thereby placed in the standby mode and powered from the battery. When in this mode, the primary battery voltage detection and the secondary battery recharging operations are stopped.

Note: To guarantee backup operation in case of momentary power failure, make sure the 5 V-to-0 V fall time on V<sub>IN</sub> is 50 µs or more by using, for example, a capacitator.



### 2. Alarm Operation

If the primary battery voltage decreases while the power supply voltage ( $V_{IN}$ ) is greater than or equal to  $V_{INH}$  (4.3 V typ), alarm signals are output as described below. At this time, if the  $V_{BAT1}$  pin is released open, the output from the alarm pin becomes indeterminate.

### (1) Primary battery replacement alarm (alarm-1 output)

If the primary battery voltage drops to  $V_{BAT1}$  (2.65 V typ), the ALARM1 pin is forced to a Low level to issue an alarm indicating that it's time to replace the primary battery.

### (2) Primary battery minimum voltage alarm (alarm-2 output)

If the primary battery voltage further drops to  $V_{BAT2}$  (2.37 V typ), the ALARM2 pin is forced to a Low level to issue an alarm indicating that the primary battery power has dropped below the voltage necessary to retain the SRAM data (approx. 2.0 V).

### ABSOLUTE MAXIMUM RATINGS

					(Ta = +25°C
Parameter	Symbol	Condit	ions	Rating	Unit
Input voltage	Vin			-0.3 to 6	V
Battery voltage				-0.3 to 6	V
Reset output Voltage			- 0.3 to Vout + 0.3 (≤ 6)	V	
Alarm output Voltage	Valarm			- 0.3 to V <sub>IN</sub> + 0.3 (≤ 6)	V
Output current	Ιουτ			250	mA
Output high current	Іон	Source current		6	mA
Output low current	Iol	Sink cu	irrent	6	mA
Dower dissipation	PD	Ta ≤ +25°C	SSOP	450*	mW
Power dissipation		$1a \ge +25^{\circ}C$	SOP	540*	mW
Storage temperature	Tstg	_		-55 to +125	°C

\*: When mounted on a 4 cm-square double-side epoxy board.

**WARNING:** Permanent device damage may occur if the above ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

## ■ RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Conditions	Value			Unit
Farameter	Symbol	Conditions	Min.	Тур.	Max.	Onit
Input voltage	Vin		—	5.0	5.5	V
Battery voltage V <sub>BAT</sub>		—		3.0	3.3	V
Output current	Іоит		0		200	mA
Output current during	IO(BAT1)	Supply from the primary battery			500	
battery backup	IO(BAT2)	Supply from the secondary battery		_	50	μA
Operating temperature	Тор		-30		+70	°C

# ■ ELECTRICAL CHARACTERISTICS

### • DC characteristics

(Recommended operating conditions unless otherwise noted.)

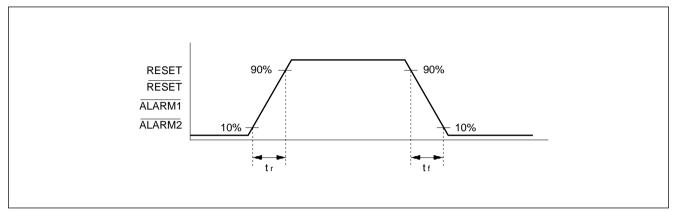
(					(VIN = +5	5 V, Ta =	+25°C)
	Parameter		Conditions	Value			Unit
		Symbol	Conditions	Min.	Тур.	Max.	
All sections	Input current	IIN1	louт = 0 mA		50	100	μA
Backup	Input/output voltage	DV <sub>1</sub>	louт = 1 mA		0.5	10	mV
Power Supply	difference	DV <sub>2</sub>	Іоит = 200 mA		100	300	mV
Section	Output delay time	tro	$C_0 = 0.01 \ \mu$ F, $C_T = 0$		2.0	10	μs
		VINL	VIN	4.10	4.20	4.30	V
	Input low voltage detection		$Ta = -30^{\circ}C \text{ to } + 70^{\circ}C$	4.05	4.20	4.35	V
		VINH	VIN	4.20	4.30	4.40	V
			$Ta = -30^{\circ}C \text{ to } + 70^{\circ}C$	4.15	4.30	4.45	V
_	Input low voltage hysteresis width	DVIN	VINH -VINL	50	100	150	mV
Power Supply	Deset sutratively as	Vohr	Іонк <b>= 1 m</b> A	4.5	4.8	—	V
Monitoring	Reset output voltage	Volr	Iolr = 5 mA		0.2	0.4	V
Section	Reset output voltage during backup V IN = 0 V VBAT1 = 3 V	Vohr	Іонк = 0.2 mA	2.2	2.6	_	V
		Volr	IOLR = 3 mA	_	0.2	0.4	V
	Reset pulse width	tро	C- 1000 pF	0.5	1.0	2.0	ms
	Input pulse width	tрi	—— C⊤ = 1000 pF		-	_	μs
	Reset output rise time	trR	C⊤ = 1000 pF		2.0	3.0	μs
	Reset output fall time	<b>t</b> fR	C∟ = 100 pF		0.2	1.0	μs
	Reset output delay time	<b>t</b> pdR	V <sub>IN</sub> slew rate < 0.1 V/µs		2.0	10	μs

# MB3790

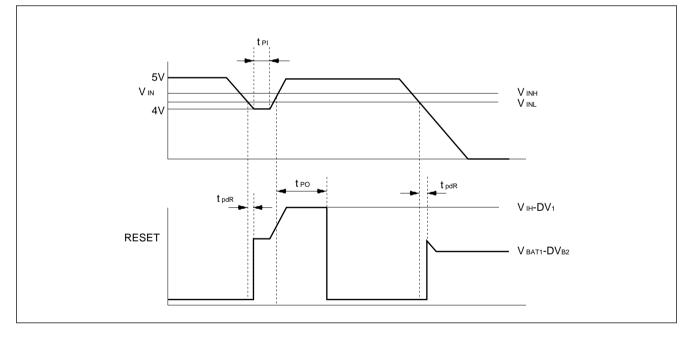
					Value			
	Parameter	Symbol	Conditions			Max.	Unit	
		VBATL1	VBAT	2.55	2.65	2.75	V	
	Low value as detection 4		$Ta = -30^{\circ}C \text{ to } +70^{\circ}C$	2.52	2.65	2.78	V	
	Low voltage detection 1	VBATH1	Vват	2.59	2.69	2.79	V	
			$Ta = -30^{\circ}C \text{ to } +70^{\circ}C$	2.56	2.69	2.82	V	
	Low voltage detection-1 hysteresis width	DVBAT1	Vbath1 — Vbatl1	20	40	60	mV	
		VBATL2	VBAT	2.27	2.37	2.47	V	
	Low voltage detection 2		$Ta = -30^{\circ}C \text{ to } +70^{\circ}C$	2.24	2.37	2.50	V	
		VBATH2	VBAT	2.31	2.41	2.51	V	
Battery-1 Monitoring			$Ta = -30^{\circ}C \text{ to } +70^{\circ}C$	2.28	2.41	2.54	V	
Section	Low voltage detection-2 hysteresis width	DVBAT2	Vbath2 - Vbatl2	20	40	60	mV	
	Low voltage detection difference	DVBAT	BAT VBATL1 - VBATL2		0.28	0.30	V	
	Battery-1 input current	Івата	$V_{BAT} = 3 V, V_{IN} = 0 V$	-100	-	500	nA	
		Іватв	VBAT = 3 V, VIN = 5 V	-100	_	500	nA	
	Battery-1 output voltage difference during backup, CTL = GND	DV <sub>B1</sub>	Ibat1 = 100 μA		0.30	0.35	V	
			I <sub>BAT1</sub> = 10 μA	_	0.10	0.15	V	
	Alarm output voltage	Vона	Iона = 4 mA	4.5	4.8	_	V	
		Vola	Iola = 5 mA	_	0.2	0.4	V	
	Alarm output rise time	trA	0 400 F	_	2.0	3.0	μs	
	Alarm output fall time	<b>t</b> fA	- C∟ = 100 pF	_	0.2	1.0	μs	
	Alarm output delay time	<b>t</b> pdA	50 mV overdrive	_	2.0	10	μs	
	Battery-2 recharging voltage	Vснg	Існа = -10 µА	2.80	3.00	3.20	V	
Battery-2 Monitoring	Battery-2 recharging current	Існа	Vснд = 2.0 V	1.0	2.0	—	mA	
Section	Battery-2 output voltage difference during backup	DV <sub>B2</sub>	Ι <sub>ΒΑΤ2</sub> = 10 μΑ	_	0.10	0.15	v	

### ■ TIMING CHART

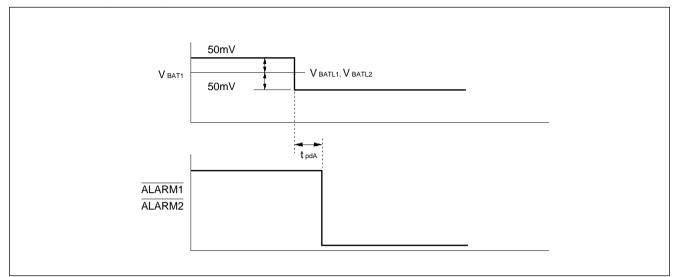
### 1. Rise/Fall Times on Reset and Alarm Pins: tr/tf



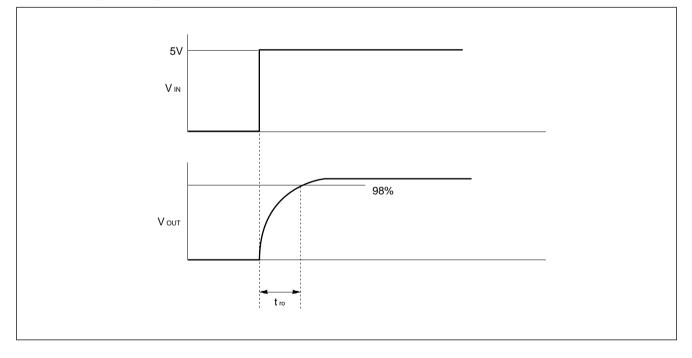
# 2. Reset Pulse Width: tpo; Input Pulse Width: tpi; Reset Output Delay Time: tpdR



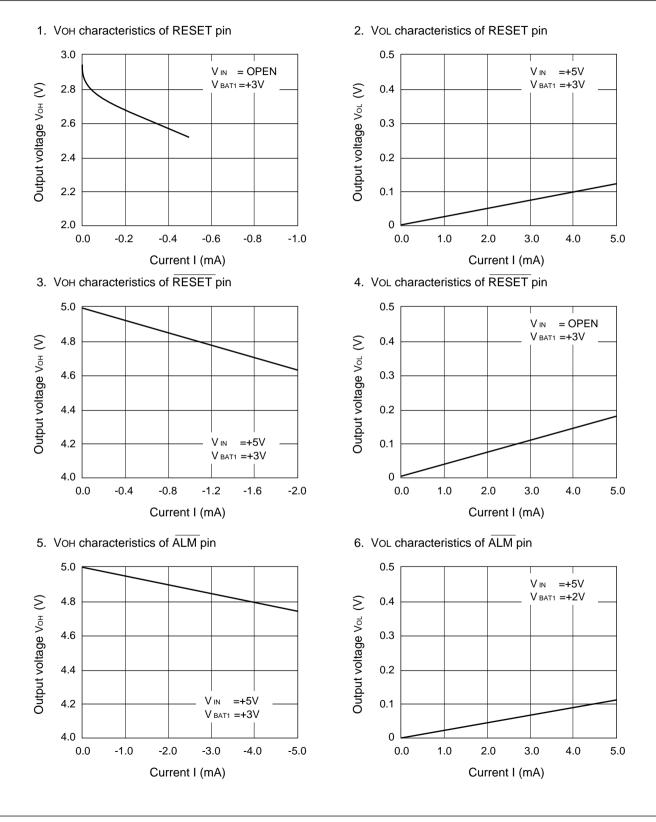
# 3. Alarm Output delay time: tpdA



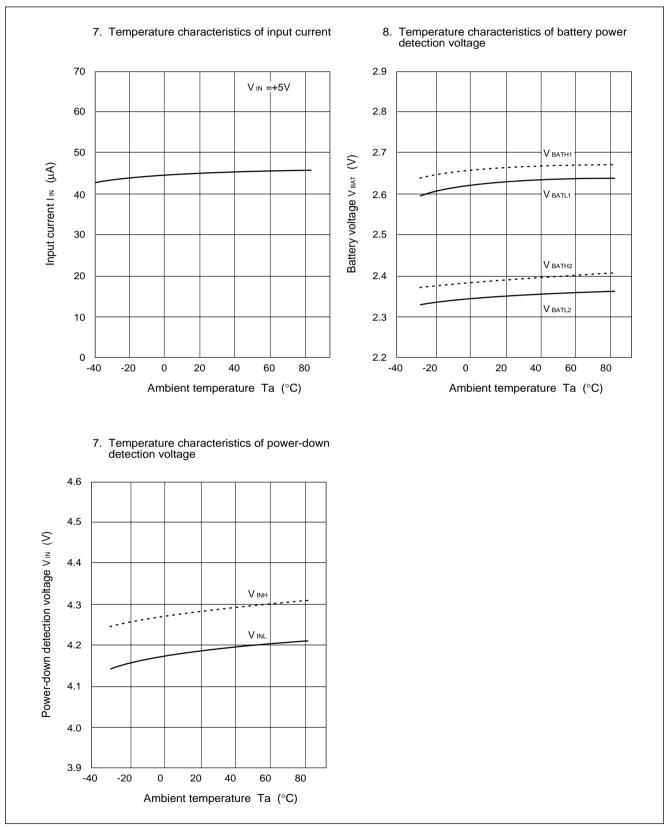
# 4. VOUT Output Delay Time: tro



# ■ TYPICAL CHARACTERISTIC CURVES



# MB3790



# ■ APPLICATION

# 1. Method of Using the CONTROL Pin

It is possible to control the operation of analog switch 1 by entering a High or Low level to the CONTROL pin while being powered by the battery. The Table below shows how the analog switch operates when its operation is controlled from the CONTROL pin.

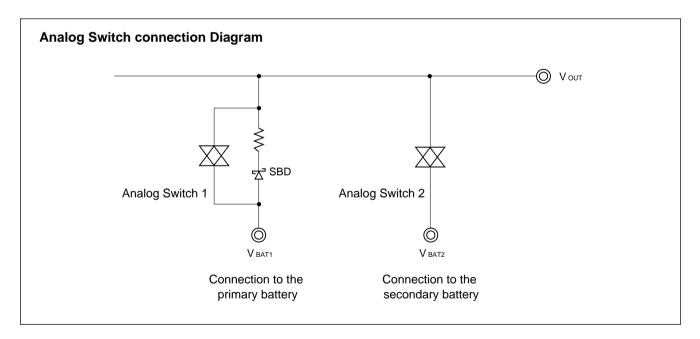
When using the primary and the secondary batteries in combination as in the case of memory cards, be sure to set the CONTROL pin High to prevent the primary battery from being recharged by the secondary battery current flowing from analog switch 1.

### • Control Conditions of CONTROL Pin

Operating state	Control c	onditions	ON/OFF State of analog switch*2		
Operating state	Input voltage (VIN)	CONTROL pin*1	Analog switch 1	Analog switch 2	
Standby/active state	VIN > VINL	High/Low	OFF	OFF	
Backup state	VINL > VIN	High (= Vout)	OFF	ON	
Backup State	VINL > VIN	Low (= GND)	ON	ON	

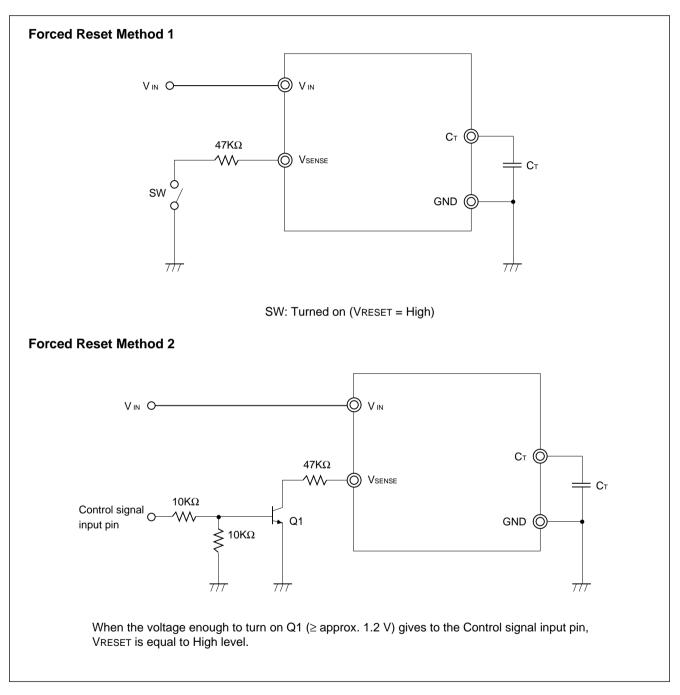
\*1: If the CONTROL pin is released open, the logic state of the CMOS circuit may become instable letting current flow into the circuit. Therefore, the CONTROL pin must always have a High or Low level input.

\*2: The ON-resistance of the analog switch is approximately 10 K ohms.



### 3. Outputting Reset Signal Forcibly

The reset signal can be output forcibly by bringing the  $V_{SENSE}$  pin of the MB3790 to a Low level (< 1.24). The reset signal is held on until the capacitator  $C_T$  is charged up after the  $V_{SENSE}$  pin is released open.



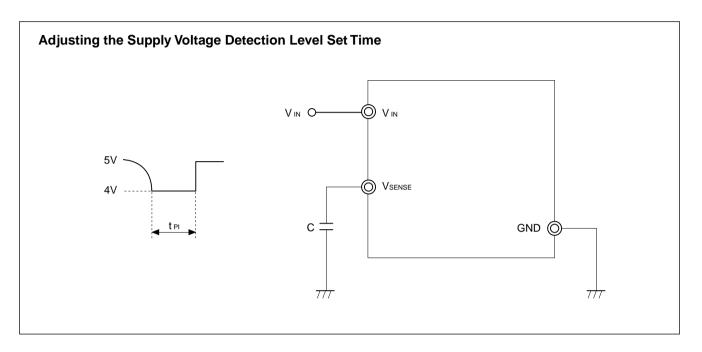
[Reset Pulse Width Calculation Formula]

Reset Pulse Width tPO (sec) =  $C_T$  (F) ×10<sup>6</sup> (where  $C_T$  = capacitance)

Example: When  $C_T = 1000 \text{ pF}$ ,  $t_{PO} = 1 \text{ ms}$  (Typ)

### 4. Adjusting the Supply Voltage Detection Level Set time

The MB3790 outputs a reset signal when the power supply momentarily goes down or its voltage sags for 5 µs or more. The set time before this reset signal is output can be extended by connecting a capacitor to the VSENSE pin.



## 5. Compatibility with JEIDA Memory Card Guideline Ver. 4

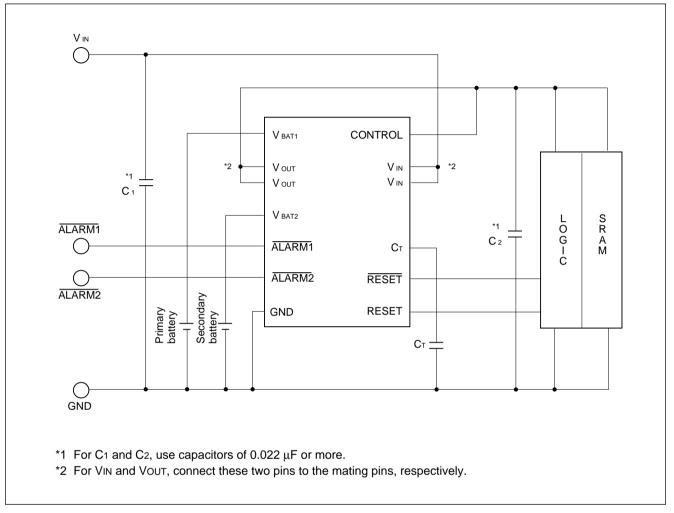
The MB3790 has its ALM1 and ALM2 pin specifications matched to the BVD2 and BVD1 pin specifications of the JEIDA Memory Card Guideline Ver. 4. Therefore, the ALM1 and ALM2 pins can be connected directly to the BVD2 and BVD1 pins.

### • Alarm Pin Detection Voltage Levels

Pin Name	$V_{\text{BAT1}} \leq 2.37 \text{ V}$	$\textbf{2.37 V} < \textbf{V}_{\text{BAT1}} \leq \textbf{2.65V}$	$\textbf{2.65 V} \leq \textbf{V}_{\text{BAT1}}$	Connected Pin
ALM1	Low level	Low level	High level	BVD2
ALM2	Low level	High level	High level	BVD1

VBAT1: Primary battery voltage

# ■ STANDARD DEVICE CONFIGURATION



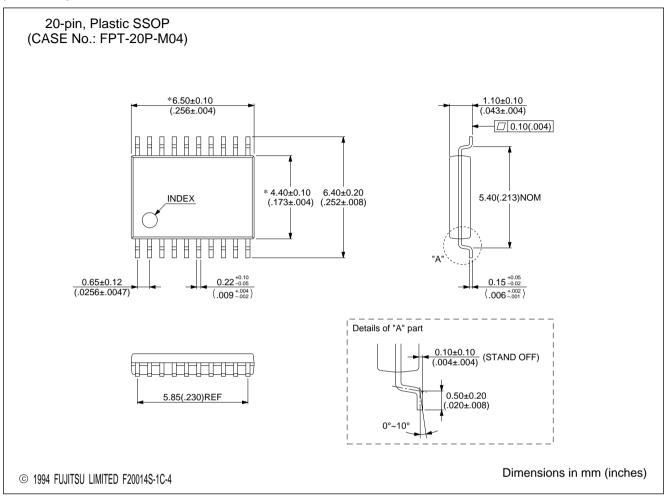
# ■ ORDERING INFORMATION

Part number	Package	Remarks
MB3790PF	16 pin, Plastic SOP (FPT-16P-M06)	
MB3790PFT	20 pin, Plastic SSOP (FPT-20P-M04)	

#### ■ PACKAGE DIMENSIONS 16-pin, Plastic SOP (FPT-16P-M06) 2.25(.089)MAX $10.15^{\,+0.25}_{\,-0.20} \bigl(.400^{\,+.010}_{\,-.008}\bigr)$ 0.05(.002)MIN (STAND OFF) 6.80+0.20 5.30±0.30 (.209±.012) 7.80±0.40 (.307±.016) INDEX (.268 +.016 ) "B" Ť Ť 0.15<sup>+0.05</sup><sub>-0.02</sub> (.006<sup>+.002</sup><sub>-.001</sub>) 0.45±0.10 (.018±.004) ⊕ Ø0.13(.005) ₪ 0.50±0.20 (.020±.008) <u>1.27(.050)</u> TYP Details of "A" part Details of "B" part 0.40(.016) 0.15(.006) 0.20(.008) "A" 0.20(.008) 0.10(.004) 0.18(.007)MAX 0.18(.007)MAX 8.89(.350)REF 0.68(.027)MAX 0.68(.027)MAX Dimensions in mm (inches) © 1994 FUJITSU LIMITED F16015S-2C-4

# MB3790

(Continued)



Since the SSOP (FPT-20P-M04) is built in an extremely thin structure, use a partial heating method when mounting the device.

# **FUJITSU LIMITED**

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